

Atty. Dkt. AZMT/001  
Serial No. 09/997,937  
Supplemental Amendment

**In the Claims:**

1. (Previously presented) A method of packaging components, comprising:  
forming an enclosure including a plurality of covers having an air-cavity, each of said covers comprising a vent hole;  
mounting a plurality of components a carrier;  
applying a curable adhesive between said enclosure and said carrier,  
aligning said enclosure with the carrier such that each component is covered by one of said air-cavity covers;  
curing said adhesive, said vent hole providing for the escape of water and other gasses that may off-gas during the curing process from said air cavity;  
sealing said vent holes with a curable material;  
curing said sealing material; and  
separating the enclosure and carrier to form a plurality of component package assemblies.
2. (Original) The method of claim 1, wherein the components comprise at least one component die.
3. (Original) The method of claim 1, wherein the enclosure is formed of materials comprising polymers, ceramic, glass, and combinations thereof.
4. (Previously presented) The method of claim 1, wherein forming comprises molding.
5. (Previously presented) The method of claim 1, wherein providing the adhesive between the enclosure and the carrier comprises applying an adhesive to the carrier.
6. (Previously presented) The method of claim 1, wherein providing an adhesive

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between the enclosure and the carrier comprises applying adhesive to a cover surface disposed adjacent the carrier.

7. (Previously presented) The method of claim 1, wherein each of said covers comprises sidewalls.
8. (Original) The method of claim 7, wherein separating comprises cutting between each of the pluralities of component through a plurality of sidewalls and the carrier.
9. (Original) The method of claim 8, wherein cutting comprises sawing, laser cutting, water cutting, milling, machining, lathing, and combinations thereof.
- 10 – 18. (Canceled)
19. (Withdrawn) An apparatus for enclosing at least one component, comprising:  
a plurality of separable sidewalls disposed on a top member wherein the separable sidewalls and top member define a plurality of separable individual component packages to enclose the at least one component therein.
20. (Withdrawn) The apparatus of claim 19, wherein when separated, the sidewalls and top member define an individual component enclosure.
21. (New) A method of forming a cover assembly comprising:  
molding a cover assembly for electronic components having a plurality of cavities formed in a unitary body, where each cavity is defined by a top and at least one side wall, the top having a vent hold extending into each cavity.

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22. (New) The method of claim 21 wherein the molding step is performed by injection molding.
23. (New) The method of claim 21 wherein the cover assembly is fabricated of at least one of thermoplastic, polymer, ceramic and glass.
24. (New) A method of packaging components comprising:  
molding a cover assembly having a plurality of cavities where each cavity is defined by a top and at least one side wall, the top having a vent hole into each cavity;  
supplying a carrier having a plurality of components mounted thereto;  
aligning the cover assembly with the carrier such that each cavity covers at least one component;  
bonding the cover assembly to the carrier; and  
separating the cover assembly and carrier to form a plurality of package assemblies.
25. (New) The method of claim 24 wherein the step of bonding comprises applying at least one of glue or epoxy between the cover assembly and carrier.
26. (New) The method of claim 24 wherein the cover assembly is fabricated of at least one of thermoplastic, polymer, ceramic and glass.
27. (New) The method of claim 24 wherein the bonding step comprises:  
applying an adhesive between the at least one sidewall and the carrier;  
curing the adhesive; and  
sealing the vent hole in each cavity.